

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Ishiwa, et al.

Group Art Unit 2841

Appl. No. : 09/779,691

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: United States Patent and Trademark Office, P.O. Box 2327, Arlington, VA 22202, on

Filed : February 7, 2001

For : MULTILAYER CIRCUIT BOARD

January 21, 2003

(Date _____)

Thomas R. Arno, Reg. No. 40,49

Examiner : Kamand Cuneo

AMENDMENT AND RESPONSE TO OFFICE ACTION

United States Patent and Trademark Office
PO Box 2327
Arlington, VA 22202

Dear Sir:

In response to the Office Action mailed July 18, 2002, Applicant respectfully submits the following amendments and remarks in connection with the above-captioned application.

IN THE DRAWINGS:

Please approve the drawing changes in RED on the attached drawings.

Please substitute the attached Figures 1-10 for Figures 1-10 as filed.

IN THE CLAIMS:

Please cancel Claim 11 without prejudice.

Please amend Claim 1 as follows.

1. (Twice Amended) A multilayer circuit board having a multilayer structure, comprising: